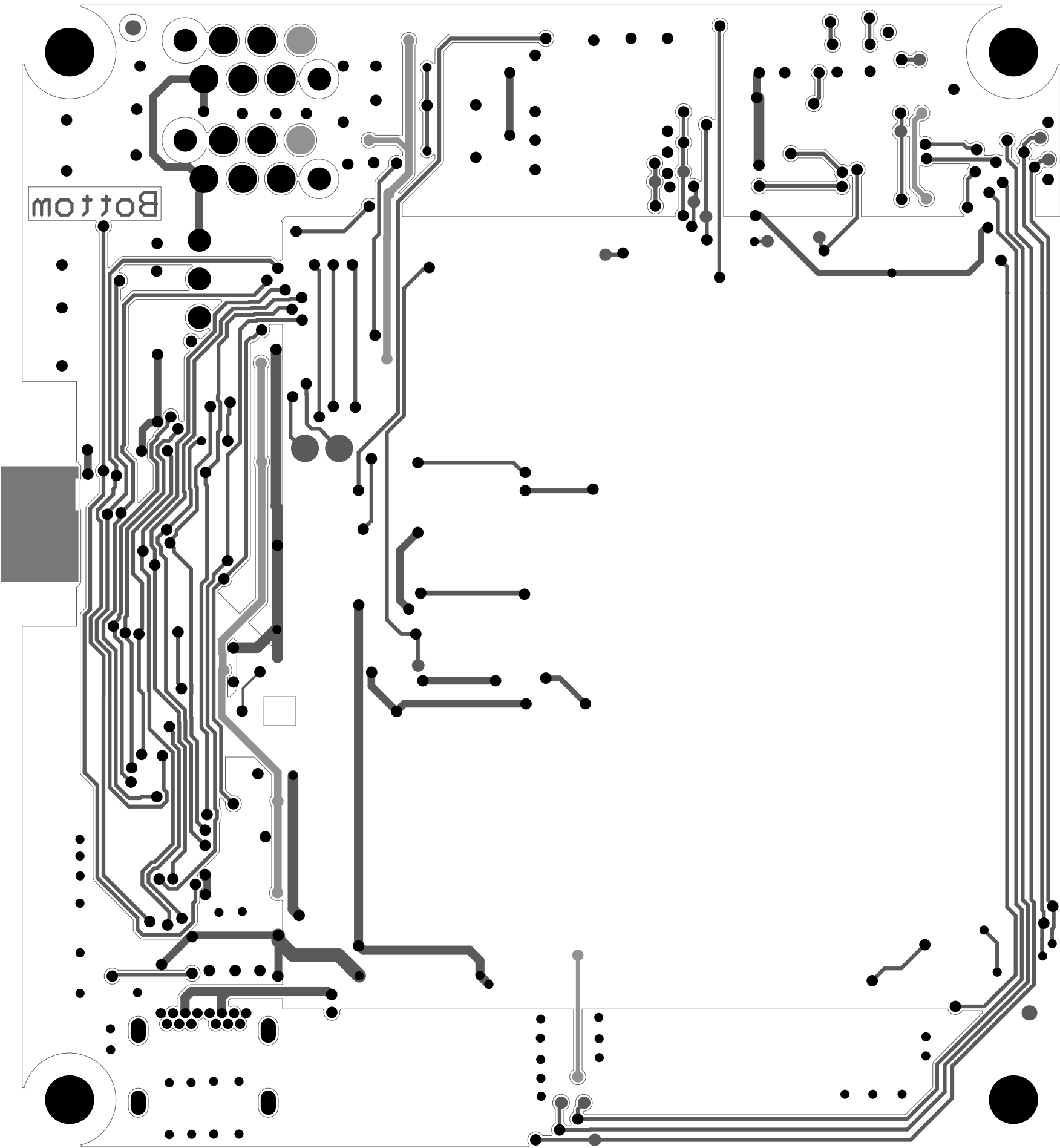




Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	SM-001	0.025mm	4	
	Top Surface Finish	PbSn	0.020mm		
1	Top Layer	CF-004	0.035mm		
	Dielectric 1	Core-043	1.499mm	4.3	
2	Bottom Layer	CF-004	0.035mm		
	Bottom Surface Finish	PbSn	0.020mm		
	Bottom Solder	SM-001	0.025mm	4	
	Bottom Overlay				

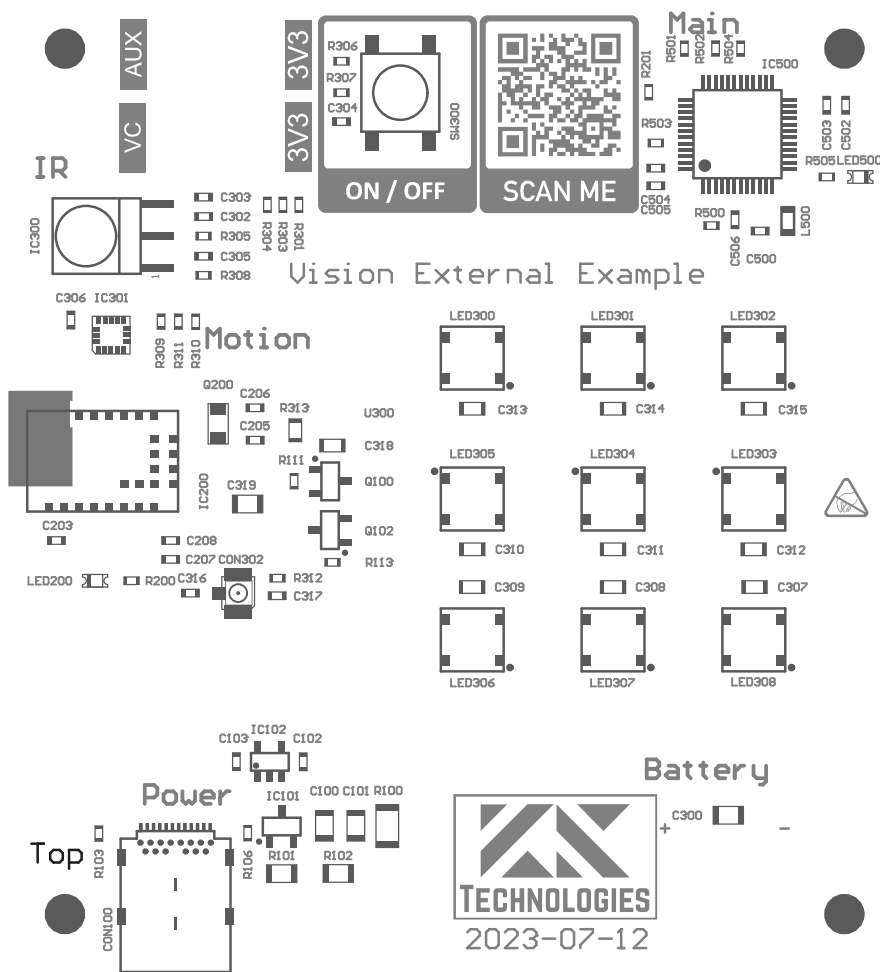
Notes		Technical PCB Data All declarations corresponding to IPC	For not tolerated measures it is: ISO 2768 medium		Deburr and break sharp edges	Weight/	
	PCB-Type	Rigid		Date	Name	Project/	
	Material	FR4	drawn	202-07-12	JK	Vision_ternal_Modle	
	Layer Count	4	checked				
	Thickness	1.6mm	saved			Board./	Scale/
	End Copper	35µm				Mainboard	1:1
	Solder Resist	Black					
	Silk Screen	White				Board Revision	
	Surface	ENIG				1.0	





Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	SM-001	0.025mm	4	
	Top Surface Finish	PbSn	0.020mm		
1	Top Layer	CF-004	0.035mm		
	Dielectric 1	Core-043	1.499mm	4.3	
2	Bottom Layer	CF-004	0.035mm		
	Bottom Surface Finish	PbSn	0.020mm		
	Bottom Solder	SM-001	0.025mm	4	
	Bottom Overlay				

Notes		Technical PCB Data All declarations corresponding to IPC	For not tolerated measures it is: ISO 2768 medium		Deburr and break sharp edges	Weight/		
	PCB-Type	Rigid		Date	Name	Project/		
	Material	FR4	drawn	202-07-12	JK	Vision_ternal_Modle		
	Layer Count	4	checked					
	Thickness	1.6mm	saved			Board./	Scale/	
	End Copper	35µm				Mainboard	1:1	
	Solder Resist	Black						Board Revision
	Silk Screen	White					1.0	
	Surface	ENIG						Sheet 1



Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	SM-001	0.025mm	4	
	Top Surface Finish	PbSn	0.020mm		
1	Top Layer	CF-004	0.035mm		
	Dielectric 1	Core-043	1.499mm	4.3	
2	Bottom Layer	CF-004	0.035mm		
	Bottom Surface Finish	PbSn	0.020mm		
	Bottom Solder	SM-001	0.025mm	4	
	Bottom Overlay				

Notes		Technical PCB Data All declarations corresponding to IPC	For not tolerated measures it is: ISO 2768 medium		Deburr and break sharp edges	Weight/	
	PCB-Type	Rigid		Date	Name	Project/	
	Material	FR4	drawn	202-07-12	JK	Vision_ternal_Modle	
	Layer Count	4	checked				
	Thickness	1.6mm	saved			Board./	
	End Copper	35µm				Mainboard	
	Solder Resist	Black				Board Revision	
	Silk Screen	White				1.0	
	Surface	ENIG					
						Sheet 1	








Bottom



Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	SM-001	0.025mm	4	
	Top Surface Finish	PbSn	0.020mm		
1	Top Layer	CF-004	0.035mm		
	Dielectric 1	Core-043	1.499mm	4.3	
2	Bottom Layer	CF-004	0.035mm		
	Bottom Surface Finish	PbSn	0.020mm		
	Bottom Solder	SM-001	0.025mm	4	
	Bottom Overlay				

Notes		Technical PCB Data All declerations corresponding to IPC	For not tolerated measures it is: ISO 2768 medium		Deburr and break sharp edges	Weight/	
	PCB-Type	Rigid		Date	Name	Project/	
	Material	FR4	drawn	202-07-12	JK	Vision_ternal_Modle	
	Layer Count	4	checked				
	Thickness	1.6mm	saved			Board./	
	End Copper	35µm				Mainboard	
	Solder Resist	Black				Board Revision	
	Silk Screen	White				1.0	
	Surface	ENIG					
		Scale/					
		1:1					
		Sheet 1					

# Board Stack Report

Stack Up		Layer Stack			
Layer	Board Layer Stack	Name	Material	Thickness	Constant
1		Top Overlay		0mm	
2		Top Solder	SM-001	0.0254mm	4
3		Top Surface Finish	PbSn	0.02mm	
4		Top Layer	CF-004	0.035mm	
5		Dielectric 1	Core-043	1.4986mm	4.3
6		Bottom Layer	CF-004	0.035mm	
7		Bottom Surface Finish	PbSn	0.02mm	
8		Bottom Solder	SM-001	0.0254mm	4
9		Bottom Overlay		0mm	
	Height : 1.6594mm				





